SCLS470A - MARCH 2003 - REVISED OCTOBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Low Input Current of 1 μA Max
- High-Current Outputs Drive Up To 10 LSTTL Loads



			1
1CLR	1	0 16] v _{cc}
1J [2	15	2CLR
1 K [3	14] 2J
1CLK	4	13] 2K
1PRE	5	12	2CLK
1Q [6	11	2PRE
1Q [7	10] 2Q
GND [8	9] 2 <mark>Q</mark>

- Low Power Consumption, 40-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ±4-mA Output Drive at 5 V



NC - No internal connection

description/ordering information

These devices contain two independent J- \overline{K} positive-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and \overline{K} inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the J and \overline{K} inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

T _A	PACKA	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC109N	SN74HC109N
–40°C to 85°C		Tube of 40	SN74HC109D	
	SOIC – D	Reel of 2500	SN74HC109DR	HC109
		Reel of 250	SN74HC109DT	
	SOP – NS	Reel of 2000	SN74HC109NSR	HC109
	CDIP – J	Tube of 25	SNJ54HC109J	SNJ54HC109J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC109W	SNJ54HC109W
	LCCC – FK	Tube of 55	SNJ54HC109FK	SNJ54HC109FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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-		FUNC	TION T	ABLE	_	
		INPUTS			OUTI	PUTS
PRE	CLR	CLK	J	ĸ	Q	Q
L	Н	Х	Х	Х	Н	L
н	L	Х	Х	Х	L	Н
L	L	Х	Х	Х	H‡	H‡
н	Н	\uparrow	L	L	L	Н
н	Н	\uparrow	Н	L	Тор	ggle
н	Н	\uparrow	L	Н	Q0	$\overline{Q}0$
н	Н	\uparrow	Н	Н	Н	L
Н	Н	L	Х	Х	Q0	$\overline{Q}0$

[†] This configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.

logic diagram, each flip-flop (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		$\pm 20 \text{ mA}$
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})		$\pm 20 \text{ mA}$
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		$\pm 35 \text{ mA}$
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ_{JA} (see Note 1): D package		73°C/W
N package		67°C/W
NS package		64°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: FK, J, or W packages		. 300°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or NS packages		. 260°C
Storage temperature range, T _{stg}	65°C 1	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

			SI	154HC10	9	SN	UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH High-level input voltage		$V_{CC} = 4.5 V$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2			4.2			
		$V_{CC} = 2 V$			0.3			0.5	
VIL Low-level input voltage	Low-level input voltage	$V_{CC} = 4.5 V$			0.9			1.35	V
		$V_{CC} = 6 V$			1.2			1.8	
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t/\Delta v$ Input transition rise/fall time		$V_{CC} = 4.5 V$			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.00			Т	A = 25°C	;	SN54H	IC109	SN74H	C109		
PARAMETER	TEST CO	INDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	1.9	1.998		1.9		1.9			
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4			
∨он	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V	
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84			
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
			2 V		0.002	0.1		0.1		0.1		
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1		
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V	
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33		
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33		
lı	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA	
ICC	$V_{I} = V_{CC} \text{ or } 0,$	IO = 0	6 V			4		80		40	μA	
Ci			2 V to 6 V		3	10		10		10	pF	

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

				T _A = 2	25°C	SN54F	IC109	SN74H	IC109	
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
					36		25		29	
			2 V	100		150		125		
		PRE or CLR low	4.5 V	20		30		25		
Ι.			6 V	17		25		21		
t _w Pulse duration		2 V	80		120		100		ns	
	CLK high or low	4.5 V	16		24		20			
			6 V	14		20		17		
			2 V	100		150		125		
		Data (J, K)	4.5 V	20		30		25		
			6 V	17		25		21		1
tsu	Setup time before CLK		2 V	25		40		30		ns
		PRE or CLR inactive	4.5 V	5		8		6		
		6 V	4		7		5			
			2 V	0		0		0		
th	Hold time	Data after CLK↑	4.5 V	0		0		0		ns
			6 V	0		0		0		



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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		T/	λ = 25°C	;	SN54H	IC109	SN74H	C109	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	6	10		4.2		5		
f _{max}			4.5 V	31	50		21		25		ns
			6 V	36	60		25		29		
			2 V		60	230		345		290	
	PRE or CLR	Q or Q	4.5 V		15	46		69		58	
			6 V		12	39		59		49	
^t pd			2 V		50	175		250		220	ns
	CLK	Q or Q	4.5 V		15	35		50		44	
			6 V		12	30		42		37	
			2 V		28	75		110		95	
tt		Q or Q	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	No load	35	pF



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PARAMETER MEASUREMENT INFORMATION

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns, t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-8415001VFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8415001VF A SNV54HC109W	Samples
84150012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84150012A SNJ54HC 109FK	Samples
8415001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8415001EA SNJ54HC109J	Samples
8415001FA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8415001FA SNJ54HC109W	Samples
JM38510/65304BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 65304BEA	Samples
M38510/65304BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 65304BEA	Samples
SN54HC109J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54HC109J	Samples
SN74HC109D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109	Samples
SN74HC109DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109	Samples
SN74HC109DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109	Samples
SN74HC109N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC109N	Samples
SN74HC109NE4	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC109N	Samples
SN74HC109NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109	Samples
SN74HC109NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC109	Samples
SNJ54HC109FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84150012A SNJ54HC 109FK	Samples
SNJ54HC109J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8415001EA SNJ54HC109J	Samples



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Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54HC109W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8415001FA SNJ54HC109W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC109, SN54HC109-SP, SN74HC109 :

• Catalog: SN74HC109, SN54HC109



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PACKAGE OPTION ADDENDUM

6-Feb-2020

Military: SN54HC109

• Space: SN54HC109-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

Texas Instruments





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal												
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC109DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC109NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC109DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC109NSR	SO	NS	16	2000	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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